



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50080-1TMB		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000401184						
<b>Package</b>		PG-TO220-7-12		<b>Weight*</b>		2119.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.466	0.49	0.49	4938	4938
leadframe	inorganic material	phosphorus	7723-14-0	0.272	0.01		129	
	non noble metal	iron	7439-89-6	0.908	0.04		428	
	non noble metal	copper	7440-50-8	906.793	42.79	42.84	427834	428391
	non noble metal	aluminium	7429-90-5	2.541	0.12	0.12	1199	1199
wire	non noble metal	aluminium	7429-90-5	2.541	0.12	0.12	1199	1199
encapsulation	organic material	carbon black	1333-86-4	8.810	0.42		4157	
	plastics	epoxy resin	-	96.914	4.57		45725	
	inorganic material	silicondioxide	60676-86-0	481.634	22.72	27.71	227241	277123
leadfinish	non noble metal	tin	7440-31-5	23.005	1.09	1.09	10854	10854
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	102	103
glue	plastics	Polyimide	26023-21-2	0.426	0.02	0.02	201	201
solder	non noble metal	tin	7440-31-5	0.078	0.00		37	
	noble metal	silver	7440-22-4	0.098	0.00		46	
	non noble metal	lead	7439-92-1	3.746	0.18	0.18	1767	1850
heatspreader	inorganic material	phosphorus	7723-14-0	0.175	0.01		83	
	non noble metal	iron	7439-89-6	0.584	0.03		275	
	non noble metal	copper	7440-50-8	582.824	27.50	27.54	274983	275341
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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